



## Material Content Data Sheet



<b>Sales Product Name</b>		TLS115D0EJ		<b>Issued</b>		9. January 2019		
<b>MA#</b>		MA003013984						
<b>Package</b>		PG-DSO-8-52		<b>Weight*</b>		83.72 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.123	1.34	1.34	13411	13411
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		109	
	non noble metal	zinc	7440-66-6	0.036	0.04		435	
	non noble metal	iron	7439-89-6	0.728	0.87		8692	
wire	non noble metal	copper	7440-50-8	29.548	35.29	36.21	352924	362160
	non noble metal	copper	7440-50-8	0.062	0.07	0.07	744	744
	encapsulation	organic material	carbon black	1333-86-4	0.101	0.12		1203
plastics	plastics	epoxy resin	-	4.634	5.54		55353	
	inorganic material	silicondioxide	60676-86-0	45.638	54.51	60.17	545111	601667
leadfinish	non noble metal	tin	7440-31-5	0.695	0.83	0.83	8303	8303
plating	noble metal	silver	7440-22-4	0.725	0.87	0.87	8654	8654
glue	plastics	epoxy resin	-	0.106	0.13		1265	
	noble metal	silver	7440-22-4	0.318	0.38	0.51	3796	5061
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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